

REMARKS

Prior to a first Office Action in this application, Applicants request that the above paragraphs be amended. These amendments do not involve any new matter or objectionable changes. When the Examiner takes this application up for action, he is requested to take the foregoing into account.

It is submitted that this application is now in good order for allowance and such allowance is respectively solicited. Should the Examiner believe minor matters still remain that can be resolved in a telephone interview, the Examiner is urged to call Applicants' undersigned attorney.

Respectfully submitted,

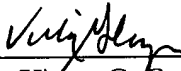
Joseph T. DiBene, II et al.

By their attorneys,

GATES & COOPER LLP

6701 Center Drive West, Suite 1050  
Los Angeles, California 90045  
(310) 641-8797

Date: August 17, 2001

By:   
Name: Victor G. Cooper  
Reg. No.: 39,641

VGC/sjm  
G&C 115.8-US-U1



APPENDIX: PARAGRAPHS IN MARKED-UP FORM

Please replace the paragraph beginning on page 2, lines 10-13 with the following:

Application Serial No. [--/---,---]09/785,892, entitled "METHOD AND APPARATUS FOR PROVIDING POWER TO A MICROPROCESSOR WITH INTEGRATED THERMAL AND EMI MANAGEMENT," by Joseph T. DiBene II, David H. Hartke, James J. Hjerpe Kaskade, and Carl E. Hoge, filed February 16, 2001; and

Please replace the paragraph beginning at page 2, lines 14-17 with the following:

Application Serial No. [--/---,---]09/798,541, entitled "THERMAL/MECHANICAL SPRINGBEAM MECHANISM FOR HEAT TRANSFER FROM HEAT SOURCE TO HEAT DISSIPATING DEVICE," by Joseph T. DiBene II, David H. Hartke, Wendell C. Johnson, and Edward J. Derian, filed March 2, 2001.

Please replace the paragraph beginning at page 2, lines 18-23 with the following:

This patent application is also related to Application Serial No. [--/---,---]09/802,329, entitled "METHOD AND APPARATUS FOR THERMAL AND MECHANICAL MANAGEMENT OF A POWER REGULATOR MODULE AND MICROPROCESSOR IN CONTACT WITH THERMALLY CONDUCTING PLATE," by Joseph T. DiBene II and David H. Hartke, filed on [same date herewith] March 8, 2001, which application is hereby incorporated by reference herein.